

SOT431-1

plastic thermal enhanced shrink quad flat package; 208 leads
(lead length 1.3 mm); body 28 x 28 x 3.4 mm; high stand-off
height; heatsink

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HSQFP208
Package type industry code	HSQFP208
Package style descriptive code	HSQFP (thermal enhanced shrink quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	20-2-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	27.9	-	28	28.1	mm
E	package width	27.9	-	28	28.1	mm
A	seated height	[tbd]	-	4.1	4.1	mm
A ₂	package height	3.2	-	3.4	3.6	mm
n ₂	actual quantity of termination	-	-	208	-	

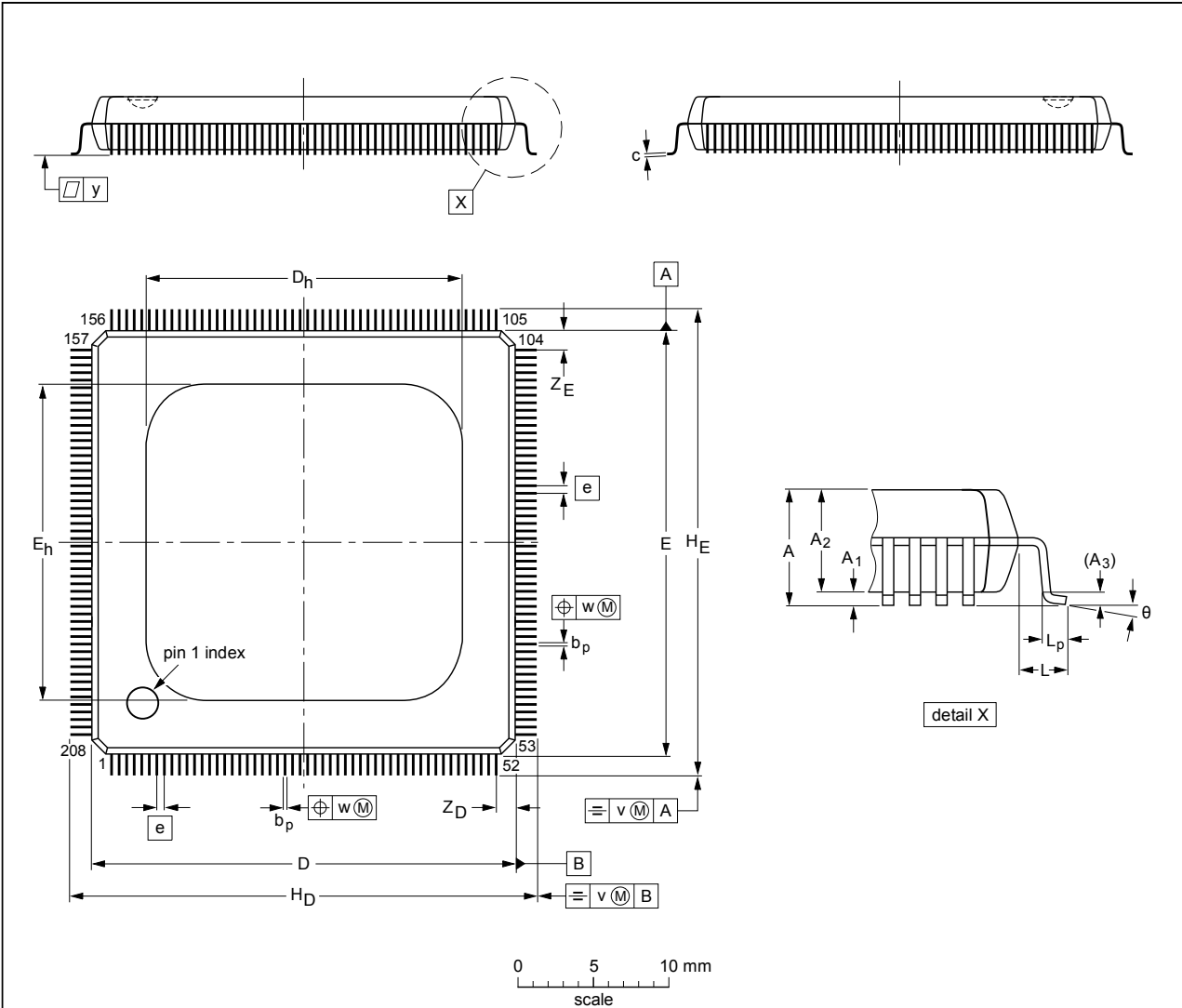


plastic thermal enhanced shrink quad flat package; 208 leads (lead length 1.3 mm); body 28 x 28 x 3.4 mm; high stand-off height; heatsink

2. Package outline

HSQFP208: plastic thermal enhanced shrink quad flat package; 208 leads (lead length 1.3 mm); body 28 x 28 x 3.4 mm; high stand-off height; heatsink

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	H _D	H _E	L	L _p	v	w	y	Z _D ⁽¹⁾	Z _E ⁽¹⁾	θ
mm	4.1	0.40 0.25	3.6 3.2	0.25	0.27 0.17	0.23 0.13	28.1 27.9	21	28.1 27.9	21	0.5	30.9 30.3	30.9 30.3	1.3	0.75 0.45	0.2	0.08	0.08	1.45 1.05	1.45 1.05	8° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT431-1					-00-02-23- 03-02-20

Fig. 1. Package outline HSQFP208 (SOT431-1)

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3. Soldering

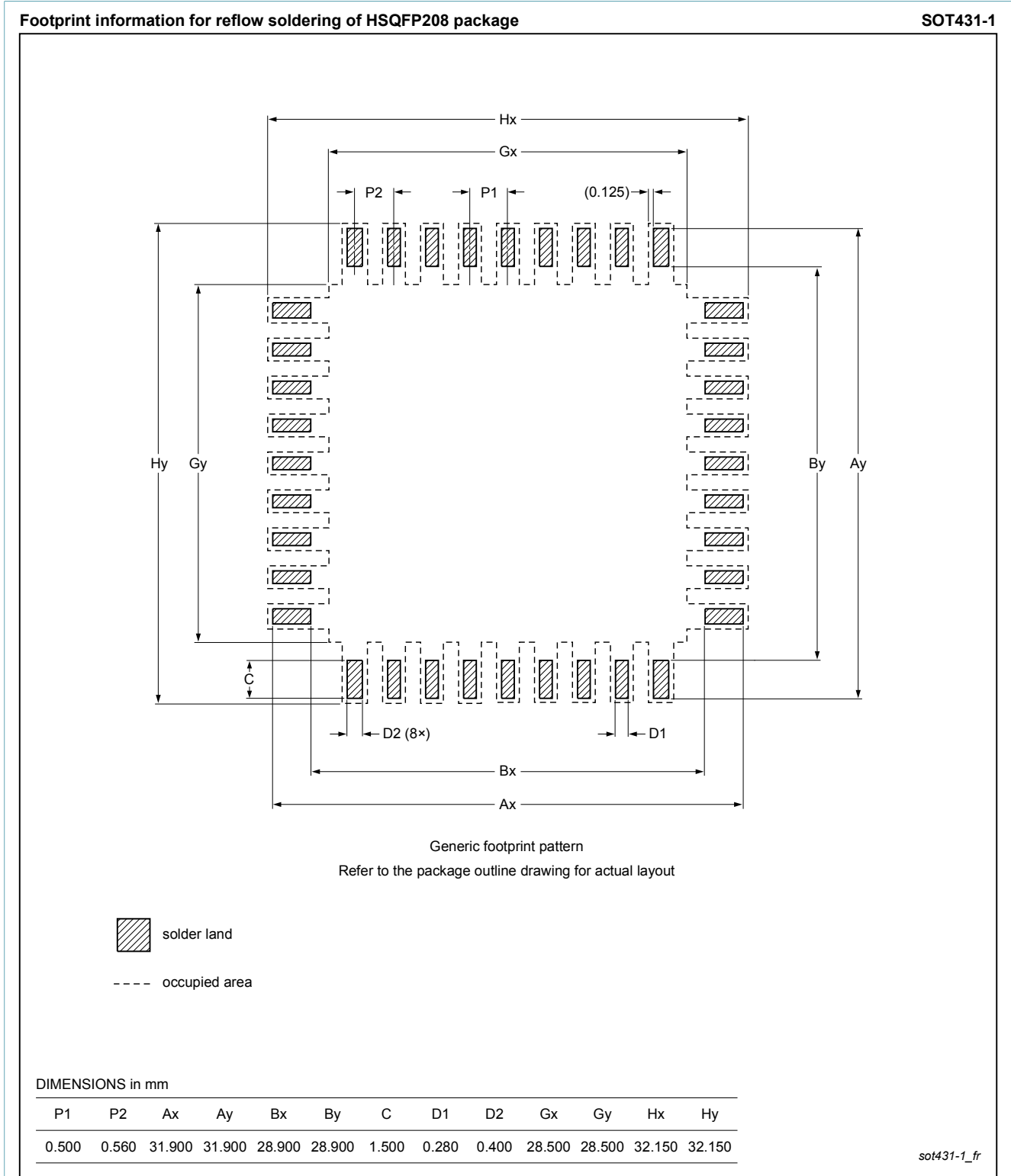


Fig. 2. Reflow soldering footprint for HSQFP208 (SOT431-1)

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4. Legal information

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For sales office addresses, please send an email to: salesaddresses@nxp.com

Date of release: 8 February 2016
